

[a peripheral drive circuit portion for driving said pixel portion;]

[an opposite] a second substrate being opposite to [said] the [element] first substrate;

a sealing member for bonding [said] the [element] first and second substrates and [said opposite substrate] together;

a substrate interval correction means being disposed in a sealing forming region where [said] the sealing material is formed [on] over the [element] first substrate,

wherein [said] the substrate interval correction means includes at least a conductive layer [not] being electrically isolated [connected to any one of the pixel portion and the peripheral drive circuit portion].

2. (Amended) A device according to claim 1,

wherein [said] the substrate interval correction means includes a same material as [said] the pixel portion.

3. (Amended) A device according to claim 1,

wherein [said] the pixel portion includes a plurality of layers each being insulated by a plurality of insulating layers, and

wherein [said] the substrate interval correction means includes a same laminate structure as [said] the pixel portion.

4. (Amended) A device according to claim 1,  
wherein a maximum value of a thickness of [said] the  
substrate interval correction means is substantially equal to a  
maximum of a thickness of [said] the pixel portion.

5. (Amended) A device according to claim 1,  
wherein a [peripheral] drive circuit portion for driving  
[said] the pixel portion is disposed between [said] the pixel  
portion and [said] the sealing material on [said] the [element]  
first substrate.

6. (Amended) [An electro-optical] A display device  
comprising:

[an element] a first substrate comprising a pixel portion  
having:

a plurality of thin film transistors;

a plurality of signal lines and a plurality of  
scanning lines which are disposed in a matrix and separated from  
each other through a first interlayer insulation film,

a plurality of pixel electrodes [being separated from  
the signal lines through a second interlayer insulation film],  
each of said pixel electrodes being electrically connected to  
each of the thin film transistors, and

[a peripheral drive circuit portion for driving said pixel portion;]

[an opposite] a second substrate being opposite to [said] the [element] first substrate;

a sealing material which surrounds [said] the pixel portion and bonds [said] the [element] first and second substrates and [said opposite substrate] together;

a substrate interval correction means being formed in a sealing forming region where [said] the sealing material is formed [on said] over the [element] first substrate, said substrate interval correction means comprising:

a first conductive layer comprising a same material as the scanning lines,

[said] the first interlayer insulation film,

a second conductive layer comprising a same material as the signal lines, and

[said] the second interlayer insulation film,

wherein [said] the first conductive layer, [said] the first interlayer insulation film, [said] the second conductive layer, and [said] the second interlayer insulation film are formed in different layers from each other.

7. (Amended) A device according to claim 6,

wherein [said] a [peripheral] drive circuit portion for driving [said] the pixel portion is disposed between [said] the pixel portion and [said] the sealing material on [said] the [element] first substrate.

8. (Amended) A device according to claim 6,

wherein an end surface of [said] the first conductive layer of the substrate interval correction means is not superimposed on an end surface of [said] the second conductive layer.

9. (Amended) A device according to claim 6,

wherein [said] the substrate interval correction means has at least a laminate structure which is identical with a region in which [said] the signal lines are superimposed on [said] the scanning lines in [said] the pixel portion.

10. (Amended) A device according to claim 6,

wherein a maximum value of a thickness of [said] the substrate interval correction means is substantially equal to a maximum of a thickness of [said] the pixel portion.

11. (Amended) A device according to claim 6 further comprising:

an external circuit being formed outside the sealing forming region or an external terminal being formed outside the [element] first substrate;

a plurality of wiring for connecting [said] the pixel portion to [said] the external circuit or [said] the external terminal,

wherein each of the plurality of wiring is formed integrally with [said] the first conductive layer, and

wherein [said] the first conductive layer extends toward an outside of [said] the sealing member.

12. (Amended) A device according to claim 6 further comprising:

an external circuit being formed outside the sealing forming region or an external terminal being formed outside the [element] first substrate;

a plurality of wiring for connecting [said] the pixel portion to [said] the external circuit or [said] the external terminal,

wherein each of the plurality of wiring is connected to [said] the first conductive layer inside [said] the sealing forming region, and

wherein [said] the first conductive layer extends toward an outside of [said] the sealing forming region.

13. (Amended) A device according to claim 6 further comprising,

an external circuit being formed outside the sealing forming region or an external terminal being formed outside the [element] first substrate,

wherein [said] the second conductive layer is [not] electrically [connected to any one of said pixel portion, said external circuit and said external terminal] isolated.

14. (Amended) A device according to claim 6,

wherein [said] the first conductive layer comprises a first plurality of linear wirings being disposed at first regular intervals, and

wherein [said] the second conductive layer comprises a second plurality of linear wirings in parallel with the signal lines or the scanning lines being disposed at second regular intervals, each of the second plurality of linear wiring being formed in a gap between the first plurality of linear wirings.

15. (Amended) A device according to claim 6,

wherein [said] the first conductive layer has a zigzag shape with substantially equal width of [said] the sealing material.

16. (Amended) A device according to claim 6,  
wherein [said] the first conductive layer is substantially  
equal to a pitch of [said] the pixel electrode.

17. (Amended) A device according to claim 6,  
wherein [said] the pixel portion further includes a  
plurality of thin-film transistors for driving [said] the pixel  
electrodes,

wherein [said] the first conductive layer is formed  
together with [said] the scanning lines, and [said] the second  
conductive layer is formed together with [said] the signal  
lines.

18. (Amended) [An electro-optical] A display device  
comprising:

[an element] a first substrate comprising a pixel portion  
having:

a plurality of signal lines and a plurality of  
scanning lines which are disposed in a matrix and separated from  
each other through a first interlayer insulation film,

a plurality of pixel electrodes disposed on cross  
points of [said] the signal lines and [said] the scanning lines  
[and separated from the signal lines through a second interlayer  
insulation film],

a plurality of thin film transistors each for operating each of the pixel electrodes, and

[a peripheral drive circuit portion for driving said pixel portion;]

[an opposite] a second substrate being opposite to [said] the [element] first substrate;

a sealing material which surrounds [said] the pixel portion and bonds [said] the [element] first and second substrates and [said opposite substrate] together;

a substrate interval correction means being formed in a sealing forming region where [said] the sealing material is formed [on said] over the [element] first substrate, said substrate interval correction means having:

at least a conductive layer comprising a same material as the scanning lines,

[said] the first interlayer insulation film, and

[said] the second interlayer insulation film,

wherein [said] the conductive layer, [said] the first interlayer insulation film, and [said] the second insulation film are formed in different layers from each other,

wherein [said] the conductive layer is [not] electrically isolated [connected to any one of the pixel portion [and the peripheral drive circuit portion].



19. (Amended) A device according to claim 18,  
wherein [said] a [peripheral] drive circuit portion for  
driving [said] the pixel portion is disposed between [said] the  
pixel portion and [said] the sealing material on [said] the  
[element] first substrate.

20. (Amended) A device according to claim 18 further  
comprising:

an external circuit being formed outside the sealing  
forming region or an external terminal being formed outside the  
[element] first substrate;

a plurality of wiring for connecting [said] the pixel  
portion to [said] the external circuit or [said] the external  
terminal,

wherein each of the plurality of wiring is formed  
integrally with [said] the conductive layer, and

wherein [said] the conductive layer extends toward an  
outside of [said] the sealing member.

21. (Amended) A device according to claim 18 further  
comprising:

an external circuit being formed outside the sealing  
forming region or an external terminal being formed outside the  
[element] first substrate;

a plurality of wiring for connecting [said] the pixel portion to [said] the external circuit or [said] the external terminal,

wherein each of the plurality of wiring is connected to [said] the conductive layer inside [said] the sealing forming region, and

wherein [said] the conductive layer extends toward an outside of said sealing forming region.

22. (Amended) A device according to claim 18,

wherein [said] the conductive layer is disposed along an edge portion of [said] the [element] first substrate and has a plurality of branches.

23. (Amended) A device according to claim 22,

wherein the branches of [said] the conductive layer are formed in an outer portion of [said] the sealing forming region.

Please add the following new claims.

24. (New) A display device comprising:

a first substrate and a second substrate;

a pixel portion being formed over the first substrate;

a plurality of thin film transistors being formed in the pixel portion;

a sealing material for bonding the first and second substrate together;

a sealing forming region where the sealing material is formed over the first substrate;

a first conductive layer being formed in the sealing forming region;

an insulating film being formed on the first plurality of wirings;

a second conductive layer being formed on the first insulating film,

wherein the first conductive layer, the first insulating film and the second conductive layer are formed in different layers from each other,

wherein each of the first conductive layer, the first insulating film and the second conductive layer is formed under the sealing material,

wherein at least one selected from the group consisting of the first and second conductive layers is electrically isolated.

25. (New) A device according to claim 24, further comprising:

a driver circuit portion for driving the pixel portion.

26. (New) A device according to claim 24,  
wherein each of the first and second conductive layers is  
electrically isolated.

27. (New) A display device comprising:  
a first substrate and a second substrate;  
a pixel portion being formed over the first substrate;  
a plurality of thin film transistors being formed in the  
pixel portion;  
a sealing material for bonding the first and second  
substrate together;  
a sealing forming region where the sealing material is  
formed over the first substrate;  
a first plurality of wirings being formed in the sealing  
forming region;  
an insulating film being formed on the first plurality of  
wirings;  
a second plurality of wirings being formed on the first  
insulating film,  
wherein the first plurality of wirings, the first  
insulating film and the second plurality of wirings are formed  
in different layers from each other,

wherein each of the first plurality of wirings, the first insulating film and each of the second plurality of wirings is formed under the sealing material,

wherein at least ones selected from the group consisting of the first plurality of wirings and the second plurality of wirings are electrically isolated.

28. (New) A device according to claim 27, further comprising:

a driver circuit portion for driving the pixel portion.

29. (New) A device according to claim 27,

wherein each of the first and second pluralities of wirings is electrically isolated.

30. (New) A display device comprising:

a first substrate and a second substrate;

a pixel portion being formed over the first substrate;

a plurality of thin film transistors being formed in the pixel portion;

a sealing material for bonding the first and second substrate together;

a sealing forming region where the sealing material is formed over the first substrate;

a first plurality of wirings being formed in the sealing forming region;

an insulating film being formed on the first plurality of wirings;

a second plurality of wirings being formed on the first insulating film,

wherein the first plurality of wirings, the first insulating film and the second plurality of wirings are formed in different layers from each other,

wherein each of the first plurality of wirings, the first insulating film and each of the second plurality of wirings is formed under the sealing material,

wherein at least ones selected from the group consisting of the first plurality of wirings and the second plurality of wirings are electrically isolated,

wherein each of the second plurality of wirings is formed in a portion where each of the first plurality of wirings is not formed.

31. (New) A device according to claim 30, further comprising:

a driver circuit portion for driving the pixel portion.

32. (New) A device according to claim 30,